



#### **General Description**

The MAX2851 is a single-chip, 5-channel RF receiver IC designed for 5GHz wireless HDMI™ applications. The IC includes all circuitry required to implement the complete 5-channel MIMO RF receiver function and crystal oscillator, providing a fully integrated receive path, VCO, frequency synthesis, and baseband/control interface. It includes a fast-settling sigma-delta RF fractional synthesizer with 76Hz frequency programming step size. The IC also integrates on-chip I/Q amplitude and phase-error calibration circuits. The receiver includes both an inchannel RSSI and also an RF RSSI.

On-chip monolithic filters are included for receiver I/Q baseband signal channel selection, for supporting both 20MHz and 40MHz RF channels. The baseband filtering and Rx signal paths are optimized to meet stringent WHDI requirements. The downconverter local oscillator is coherent among all the receiver channels.

The reverse-link control channel uses an on-chip 5GHz OFDM transmitter. It shares the RF synthesizer and LO generation circuit with the MIMO receivers. Dynamic on/off control of the external PA is implemented with programmable precision voltage. An analog mux routes external PA power-detect voltage to the RSSI pin.

The MIMO receiver chip is housed in a small 68-pin TQFN leadless plastic package with exposed paddle.

### **Applications**

5GHz Wireless HDMI (WHDI™) 5GHz FDD Backhaul and WiMAX™ 5GHz MIMO Receiver Up to Five Spatial Streams 5GHz Beam Steering Receiver

#### **Features**

- ♦ 5GHz, 5x MIMO Downlink Receivers, Single-Uplink IEEE 802.11a Transmitter
- ♦ 4900MHz to 5900MHz Frequency Range
- Coherent LO Among Receivers
- ♦ 4.5dB Rx Noise Figure
- ◆ 70dB Rx Gain Control Range with 2dB Step Size, **Digitally Controlled**
- ♦ 60dB Dynamic Range Receiver RSSI
- RF Wideband Receiver RSSI
- ♦ Programmable 20MHz/40MHz Rx I/Q Lowpass **Channel Filters**
- → -5dBm Transmit Power (54Mbps OFDM)
- ♦ 31dB Tx Gain Control Range with 0.5dB Step Size, **Digitally Controlled**
- ◆ Tx/Rx I/Q Error and LO Leakage Detection and Adjustment
- ◆ Programmable 20MHz/40MHz Tx I/Q Lowpass Anti-Aliasing Filter
- Analog Mux for PA Power Detect
- ◆ PA On/Off Control
- ◆ Sigma-Delta Fractional-N PLL with 76Hz Resolution
- ♦ Monolithic Low-Noise VCO with -35dBc Integrated **Phase Noise**
- **♦ 4-Wire SPI™ Digital Interface**
- ♦ I/Q Analog Baseband Interface
- Digital Tx/Rx Mode Control
- ♦ On-Chip Digital Temperature Sensor Readout
- **♦ Complete Baseband Interface**
- ◆ Digital Tx/Rx Mode Control
- ♦ +2.7V to +3.6V Supply Voltage
- ◆ Small 68-Pin TQFN Package (10mm x 10mm)

## Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX2851ITK+	-25°C to +85°C	68 TQFN-EP*

<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

HDMI is a trademark of HDMI Licensing, LLC. WHDI is a trademark of WHDI Special Interest Group. WiMAX is a trademark of the WiMAX Forum. SPI is a trademark of Motorola, Inc.

Typical Operating Circuit appears at end of data sheet.

/U/IXI/U

<sup>\*</sup>EP = Exposed paddle.

#### **ABSOLUTE MAXIMUM RATINGS**

VCC_ Pins to GND0.3V to +3.9V RF Inputs Max Current: RXRF1+, RXRF1-, RXRF2+, RXRF3+, RXRF3-, RXRF4+, RXRF4-,
RXRF5+, RXRF5- to GND1mA to +1mA
RF Outputs: TXRF+, TXRF- to GND0.3V to +3.9V
Analog Inputs: TXBBI+, TXBBI-, TXBBQ+, TXBBQ-, PA_DET,
XTAL, XTAL_CAP to GND0.3V to +3.9V
Analog Outputs: RXBBI1+, RXBBI1-, RXBBQ1+, RXBBQ1-,
RXBBI2+, RXBBI2-, RXBBQ2+, RXBBQ2-, RXBBI3+, RXBBI3-,
RXBBQ3+, RXBBQ3-, RXBBI4+, RXBBI4-, RXBBQ4+,
RXBBQ4-, RXBBI5+, RXBBI5-, RXBBQ5+, RXBBQ5-, RSSI,
CLKOUT2, BYP_VCO, CPOUT+, CPOUT-, PA_BIAS to
GND0.3V to +3.9V

Digital Inputs: ENABLE, CS, SCLK,
DIN to GND0.3V to +3.9V
Digital Outputs: DOUT, CLKOUT to GND0.3V to +3.9V
Short-Circuit Duration
Analog Outputs
Digital Outputs
RF Input Power+10dBm
RF Output Differential Load VSWR6:1
Continuous Power Dissipation (T <sub>A</sub> = +85°C)
68-Pin TQFN (derate 29.4mW/°C above +70°C)2352mW
Operating Temperature Range25°C to +85°C
Junction Temperature+150°C
Storage Temperature Range65°C to +160°C
Lead Temperature (soldering, 10s)+300°C
Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



#### DC ELECTRICAL CHARACTERISTICS

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_A = -25^{\circ}C$  to  $+85^{\circ}C$ , ENABLE set according to operating mode,  $\overline{CS} = \text{high}$ , SCLK = DIN = low, transmitter in maximum gain. Power matching and termination for the differential RF output pins using the *Typical Operating Circuit*, 100mV<sub>RMS</sub> differential I and Q signals applied to I and Q baseband inputs of transmitters in transmit mode. Typical values measured at  $V_{CC} = 2.85V$ ,  $T_A = +25^{\circ}C$ , LO freq = 5.35GHz. Channel bandwidth is set to 40MHz. PA control pins open circuit, VCC PA BIAS is disconnected.) (Note 1)

PARAMETER	CONDITIONS			TYP	MAX	UNITS
Supply Voltage			2.7		3.6	V
	Shutdown mode	$T_A = +25^{\circ}C$		10		μΑ
		XTAL oscillator, CLKOUT2 is off		3.7		
	Clockout only mode with load = 10pF at	XTAL oscillator, CLKOUT2 is on		4.6		
	CLKOUT pin	TCXO input, CLKOUT2 is off		4.8	7.0	
	02.1001 piii	TCXO input, CLKOUT2 is on		6.1		
	Standby mode	Standby mode		60		
Supply Current	Transmit mode			183	212	mA
	Receive mode	One receiver is on		144	184	
		Five receivers are on		367	458	
	Receive calibration mode	One receiver is on		248		
		Five receivers are on		435	517	
	Transmit calibration mode			256		
Rx I/Q Output Common-Mode Voltage			0.88	1.1	1.34	V
Tx Baseband Input Common- Mode Voltage Operating Range			0.5		1.1	V
Tx Baseband Input Bias Current	Source current			10	20	μΑ

#### DC ELECTRICAL CHARACTERISTICS (continued)

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_{A} = -25^{\circ}C$  to  $+85^{\circ}C$ , ENABLE set according to operating mode,  $\overline{CS} = \text{high}$ , SCLK = DIN = low, transmitter in maximum gain. Power matching and termination for the differential RF output pins using the *Typical Operating Circuit*; 100mV<sub>RMS</sub> differential I and Q signals applied to I and Q baseband inputs of transmitters in transmit mode. Typical values measured at  $V_{CC} = 2.85V$ ,  $V_{$ 

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS			
LOGIC INPUTS: ENABLE, SCLK, DIN, CS								
Digital Input-Voltage High, VIH		V <sub>C</sub> C - 0.4			V			
Digital Input-Voltage Low, VIL	(Note 2)			0.3	V			
Digital Input-Current High, IIH		-1		+1	μΑ			
Digital Input-Current Low, IIL		-1		+1	μΑ			
LOGIC OUTPUTS: DOUT, CLKO	UT							
Digital Output-Voltage High, VOH	Sourcing 1mA	V <sub>C</sub> C - 0.4			V			
Digital Output-Voltage Low, VOL	Sinking 1mA			0.4	V			
Digital Output Voltage in Shutdown Mode	Sinking 1mA		VoL		V			

#### AC ELECTRICAL CHARACTERISTICS—Rx MODE

(Operating conditions unless otherwise specified:  $V_{CC}=2.7V$  to 3.6V,  $T_A=-25^{\circ}C$  to  $+85^{\circ}C$ , RF freq = 5.351GHz, LO freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low, with power matching at RXRF\_+ and RXRF\_- differential ports using the *Typical Operating Circuit*. Receiver I/Q output at  $100mV_{RMS}$  loaded with  $10k\Omega$  differential load resistance and 10pF load capacitance. RSSI pin is loaded with  $10k\Omega$  load resistance to ground. Typical values measured at  $V_{CC}=2.85V$ ,  $T_A=+25^{\circ}C$ , channel bandwidths of 40MHz.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
RECEIVER SECTION: RF INPUT Includes 50 $\Omega$ to 100 $\Omega$ RF Balun	TO I/Q BASEBAND LOADED OUTPUT and Matching				
RF Input Frequency Range		4.9		5.9	GHz
Peak-to-Peak Gain Variation Over RF Frequency Range at One Temperature	4.9GHz to 5.9GHz		1.8	4.2	dB
RF Input Return Loss	All LNA settings		-6		dB
Tatal Valta are Caire	Maximum gain, Main address 1 D[7:0] = 11111111	61.8	68		- dB
Total Voltage Gain	Minimum gain, Main address 1 D[7:0] = 00000000		-2	+6.9	T UB
	Main address 1 D[7:5] = 110		-8		
RF Gain Steps Relative to	Main address 1 D[7:5] = 101		-16		dB
Maximum Gain	Main address 1 D[7:5] = 001		-32		] UB
	Main address 1 D[7:5] = 000		-40		
Baseband Gain Range	From maximum baseband gain (Main address 1 D[3:0] = 1111) to minimum baseband gain (Main address 1 D[3:0] = 0000)	28	30	32	dB
Baseband Gain Step			2		dB
RF Gain Change Settling Time	Gain settling to within $\pm 0.5$ dB of steady state, RXHP = 1		400		ns

### AC ELECTRICAL CHARACTERISTICS—Rx MODE (continued)

(Operating conditions unless otherwise specified:  $V_{CC}=2.7V$  to 3.6V,  $T_A=-25^{\circ}C$  to  $+85^{\circ}C$ , RF freq = 5.351GHz, LO freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low, with power matching at RXRF\_+ and RXRF\_- differential ports using the *Typical Operating Circuit*. Receiver I/Q output at  $100mV_{RMS}$  loaded with  $10k\Omega$  differential load resistance and 10pF load capacitance. RSSI pin is loaded with  $10k\Omega$  load resistance to ground. Typical values measured at  $V_{CC}=2.85V$ ,  $T_A=+25^{\circ}C$ , channel bandwidths of 40MHz.) (Note 1)

PARAMETER	CONDITIONS		MIN TYP	MAX	UNITS
Baseband Gain Change Settling Time	Gain settling to within ±0	0.5dB of steady state, RXHP = 1	200		ns
	Balun input referred, integrated from 10kHz	Maximum RF gain (Main address 1 D[7:5] = 111)	4.5		
DCB Noige Figure	to 9.5MHz at I/Q base- band output for 20MHz RF bandwidth	Maximum RF gain - 16dB (Main address 1 D[7:5] = 101)	15		- dB
DSB Noise Figure	Balun input referred, integrated from 10kHz	Maximum RF gain (Main address 1 D[7:5] = 111)	4.5		] ub
	to 19MHz at I/Q base- band output for 40MHz RF bandwidth	Maximum RF gain - 16dB (Main address 1 D[7:5] = 101)	15		
	20MHz RF channel,	-65dBm wanted signal, RF gain = max (Main address 1 D[7:0] = 11101001)	-13		
	two-tone jammers at +25MHz and +48MHz frequency offset with -39dBm/tone	-49dBm wanted signal, RF gain = max - 16dB (Main address 1 D[7:0] = 10101001)	-5		
		-45dBm wanted signal, RF gain = max - 32dB (Main address 1 D[7:0] = 00111111)	11		- dBm
Out-of-Band Input IP3	40MHz RF channel, two-tone jammers at +50MHz and +96MHz frequency offset with	-65dBm wanted signal, RF gain = max (Main address 1 D[7:0] = 11101001)	-13		- UBIII
		-49dBm wanted signal, RF gain = max - 16dB (Main address 1 D[7:0] = 10101001)	-5		
	-39dBm/tone	-45dBm wanted signal, RF gain = max - 32dB (Main address 1 D[7:0] = 00101001)	11		
1dB Gain Desensitization by	Blocker at ±40MHz offse channel	et frequency for 20MHz RF	-24		
Alternate Channel Blocker	Blocker at ±80MHz offse channel	Blocker at ±80MHz offset frequency for 40MHz RF			- dBm
	Max RF gain (Main addr	ess 1 D[7:5] = 111)	-34		
Input 1dD Cain Common :	Max RF gain - 8dB (Mair	n address 1 D[7:5] = 110)	-25		alD <sub>max</sub>
Input 1dB Gain Compression	Max RF gain - 16dB (Ma	in address 1 D[7:5] = 101)	-18		dBm
	Max RF gain - 32dB (Ma	in address 1 D[7:5] = 001)	-1		

### AC ELECTRICAL CHARACTERISTICS—Rx MODE (continued)

(Operating conditions unless otherwise specified:  $V_{CC}=2.7V$  to 3.6V,  $T_A=-25^{\circ}C$  to  $+85^{\circ}C$ , RF freq = 5.351GHz, LO freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low, with power matching at RXRF\_+ and RXRF\_- differential ports using the *Typical Operating Circuit*. Receiver I/Q output at 100mV<sub>RMS</sub> loaded with 10k $\Omega$  differential load resistance and 10pF load capacitance. RSSI pin is loaded with 10k $\Omega$  load resistance to ground. Typical values measured at V<sub>CC</sub> = 2.85V, T<sub>A</sub> = +25°C, channel bandwidths of 40MHz.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output 1dB Gain Compression	Over passband frequency range, at any gain setting, 1dB compression point		0.63		
Baseband -3dB Lowpass Corner	Main address 0 D1 = 0		9.5		MHz
Frequency	Main address 0 D1 = 1		19		IVIIIZ
Baseband Filter Stopband	Rejection at 30MHz offset frequency for 20MHz channel		74		dB
Rejection	Rejection at 60MHz offset frequency for 40MHz channel		69		ub
	Main address 5 D1 = 1		600		
Baseband -3dB Highpass Corner Frequency	Main address 5 D1 = 0, Main address 4 D3 = 1		10		kHz
Comer rrequency	Main address 5 D1 = 0, Main address 4 D3 = 0 (Note 3)		0.1		
Steady-State I/Q Output DC Error with AC-Coupling	50µs after enabling receive mode and togging RXHP from 1 to 0, averaged over many measurements if I/Q noise voltage exceeds 1mV <sub>RMS</sub> , at any given gain setting, no input signal, 1-sigma value	2			mV
I/Q Gain Imbalance	1MHz baseband output, 1-sigma value		0.1		dB
I/Q Phase Imbalance	1MHz baseband output, 1-sigma value		0.2		deg
Sideband Suppression	1MHz baseband output		40		dB
	LO frequency		-75		
Receiver Spurious Signal	2x LO frequency -62			dBm/	
Emissions	3x LO frequency		-75		MHz
	4x LO frequency		-54		
RF RSSI Output Voltage	-25dBm input power		1.6		V
Baseband RSSI Slope		18	26.5	37	mV/dB
Baseband RSSI Maximum Output Voltage			2.3		V
Baseband RSSI Minimum Output Voltage			0.5		V
RF Loopback Conversion Gain	Tx VGA gain at max (Main address 9 D[9:4] = 111111), Rx VGA gain at max - 24dB (Main address 1 D[3:0] = 0101)	-17.1	-10	-1.7	dB

#### AC ELECTRICAL CHARACTERISTICS—Tx MODE

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_A = -25^{\circ}C$  to  $+85^{\circ}C$ , RF freq = 5.351GHz, LO freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low, with power matching at TXRF+ and TXRF- differential ports using the *Typical Operating Circuit*; 100mV<sub>RMS</sub> sine and cosine signal applied to I/Q baseband inputs of transmitter (differential DC-coupled). Typical values measured at  $V_{CC} = 2.85V$ ,  $T_A = +25^{\circ}C$ , channel bandwidths of 40MHz.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
TRANSMIT SECTION: Tx BASE Includes Matching and Balun L	BAND I/Q INPUTS TO RF OUTPUTS oss				
RF Output Frequency Range		4.9		5.9	GHz
Peak-to-Peak Gain Variation Over RF Band	At one temperature		0.7	1.55	dB
Maximum Output Power	20MHz OFDM signal conforming to spectral emission mask and -34dB EVM		-3		
	40MHz OFDM signal confirming to spectral emission mask and -34dB EVM		-3		dBm
Output 1dB Gain Compression	Relative to typical maximum output power at 9.5MHz input frequency		11		dBc
Input 1dB Gain Compression	At 19MHz input frequency, over input common-mode voltage between 0.5V and 1.1V		380		mVRMS
Gain Control Range		24	31.5	34	dB
Gain Control Step			0.5		dB
RF Output Return Loss			-3		dB
Unwanted Sideband	Over RF channel, RF frequency, baseband frequency, and gain settings (Note 4)		-40		dBc
Carrier Leakage	Over RF channel, RF frequency, and gain settings (Note 4)		-29	-15	dBc
T. 1/O largest large adapta (D    O)	Minimum differential resistance		60		kΩ
Tx I/Q Input Impedance (R II C)	Maximum differential capacitance		2		рF
Baseband Filter Stopband	At 30MHz frequency offset for 20MHz RF channel		86		dB
Rejection	At 60MHz frequency offset for 40MHz RF channel		67		иь
Tx Calibration Ftone Level	At Tx gain code (Main address 9 D[9:4]) = 100010 and -15dBc carrier leakage (Local address 27 D[2:0] = 110 and Main address 1 D[3:0] = 0000)		-24		dBV <sub>RMS</sub>
Tx Calibration RF Gain Step	Local address 27 D[1:0] = 01		-14		-ID
Relative to Maximum Gain	Local address 27 D[1:0] = 00		-28		dB
Tx Calibration Baseband Gain Step Relative to Maximum Gain	Local address 27 D2 = 0		-5		dB

#### AC ELECTRICAL CHARACTERISTICS—FREQUENCY SYNTHESIS

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_A = -25^{\circ}C$  to  $+85^{\circ}C$ , freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low. Typical values measured at  $V_{CC} = 2.85V$ ,  $T_A = +25^{\circ}C$ , LO freq = 5.35GHz.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
FREQUENCY SYNTHESIZER					
RF Channel Center Frequency		4.9		5.9	GHz
Channel Center Frequency Programming Step			76.294		Hz
Closed-Loop Integrated Phase Noise	Loop BW = 200kHz, integrate phase noise from 1kHz to 10MHz	-35			dBc
Charge-Pump Output Current			0.8		mA
Spur Level	fOFFSET = 0 to 19MHz	-42		dBc	
Spui Levei	foffset = 40MHz		-66		
Reference Frequency			40		MHz
Reference Frequency Input Levels	AC-coupled to XTAL pin	800			mVp-p
Maximum Crystal Motional Resistance			50		Ω
Crystal Capacitance Tuning Range	Base-to-ground capacitance		30		pF
Crystal Capacitance Tuning Step			140		fF
CLKOUT Signal Level	10pF load capacitance	VCC - 0.8	VCC - 0.1		V <sub>P-P</sub>
CLKOUT2 Signal Level	4pF load capacitance		0.3		V <sub>P-P</sub>

#### AC ELECTRICAL CHARACTERISTICS—MISCELLANEOUS BLOCKS

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_A = -25^{\circ}C$  to  $+85^{\circ}C$ . Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low. Typical values measured at  $V_{CC} = 2.85V$ ,  $T_A = +25^{\circ}C$ .) (Note 1)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
PA POWER-DETECTOR MUX						
Output Voltage Drop	VIN = 2.0V, load resistance	$e = 10k\Omega$ to ground		15	32	mV
PA ON/OFF CONTROL						
VCC_PA_BIAS Input Voltage Range			3.1		3.6	V
VCC_PA_BIAS Supply Current	With 10mA load at PA_BIAS			10.5		mA
Output High Level	10mA load current, Main a	10mA load current, Main address 11 D[7:5] = 011				V
Output Low Level	1mA load current, Main address 11 D[7:5] = 011			25		mV
Turn-On Time	Measured from CS rising edge			0.3		μs
ON-CHIP TEMPERATURE SENS	OR					
	Readout at DOUT pin	T <sub>A</sub> = +25°C		13		
Digital Output Code	through Main address 3	T <sub>A</sub> = +85°C		22		
	D[4:0]	T <sub>A</sub> = -25°C		2		

### AC ELECTRICAL CHARACTERISTICS—TIMING

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_{A} = -25^{\circ}C$  to  $+85^{\circ}C$ , freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low. Typical values measured at  $V_{CC} = 2.85V$ ,  $T_{A} = +25^{\circ}C$ , LO freq = 5.35GHz.) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
SYSTEM TIMING							
Shutdown Time					2		μs
Maximum Channel Switching Time			dth = 200kHz, settling to from steady state		2		ms
Maximum Channel Switching Time with Preselected VCO Sub-Band		Loop bandwidth = 200kHz, settling to within ±1kHz from steady state		56			μs
Rx/Tx Turnaround Time		Measured from CS ris-	Rx to Tx mode, Tx gain settles to within 0.2dB of steady state		2		
		ing edge	Tx to Rx mode with RXHP = 1, Rx gain settles to within 0.5dB of steady state		2		+ μs
Tx Turn-On Time (from Standby Mode)			m CS rising edge, Tx gain iin 0.2dB of steady state		2		μs
Tx Turn-Off Time (to Standby Mode)		From CS risin	g edge		0.1		μs
Rx Turn-On Time (from Standby Mode)		Measured from $\overline{\text{CS}}$ rising edge, Rx gain settles to within 0.5dB of steady state			2		μs
Rx Turn-Off Time (to Standby Mode)		From CS risin	g edge		0.1		μs

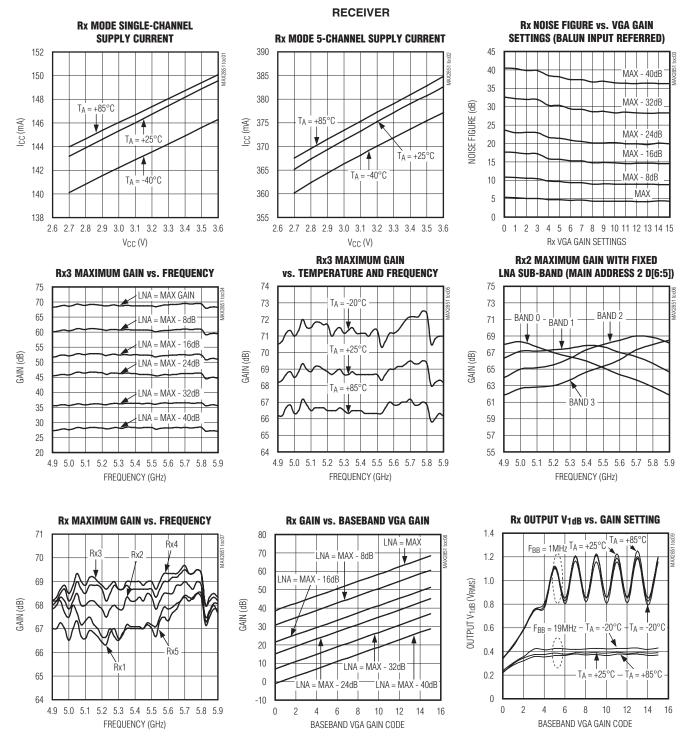
#### AC ELECTRICAL CHARACTERISTICS—TIMING (continued)

(Operating conditions unless otherwise specified:  $V_{CC} = 2.7V$  to 3.6V,  $T_{A} = -25^{\circ}C$  to  $+85^{\circ}C$ , freq = 5.35GHz. Reference freq = 40MHz, ENABLE = high,  $\overline{CS}$  = high, SCLK = DIN = low. Typical values measured at  $V_{CC} = 2.85V$ ,  $T_{A} = +25^{\circ}C$ , LO freq = 5.35GHz.) (Note 1)

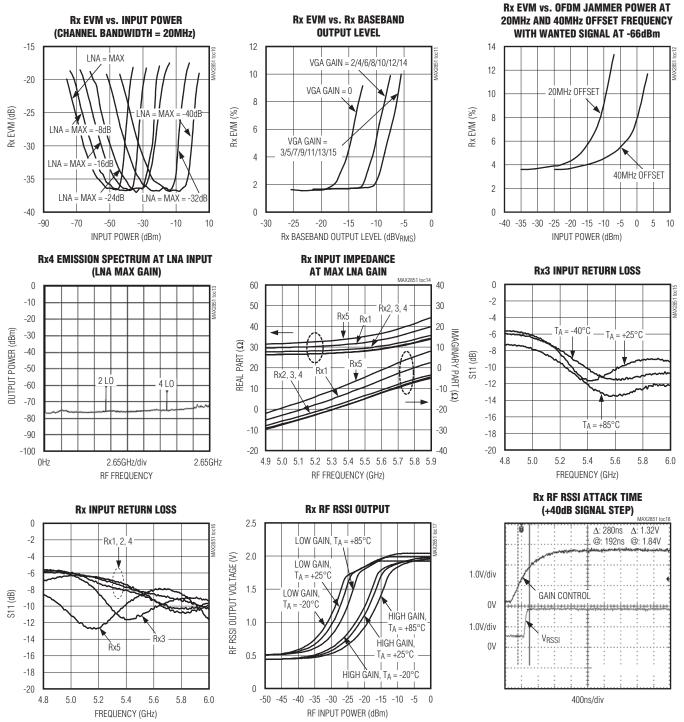
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
4-WIRE SERIAL INTERFACE TIMING (Figure 1)							
SCLK Rising Edge to CS Falling Edge Wait Time	tcso			6		ns	
Falling Edge of CS to Rising Edge of First SCLK Time	tcss			6		ns	
DIN to SCLK Setup Time	tDS			6		ns	
DIN to SCLK Hold Time	tDH			6		ns	
SCLK Pulse-Width High	tCH			6		ns	
SCLK Pulse-Width Low	tCL			6		ns	
Last Rising Edge of SCLK to Rising Edge of CS or Clock to Load Enable Setup Time	tcsh			6		ns	
CS High Pulse Width	tcsw			50		ns	
Time Between Rising Edge of CS and the Next Rising Edge of SCLK	tCS1			6		ns	
SCLK Frequency	fCLK				40	MHz	
Rise Time	t <sub>R</sub>			2.5		ns	
Fall Time	tF			2.5		ns	

- Note 1: The MAX2851 is production tested at TA = +25°C, minimum/maximum limits at TA = +25°C are guaranteed by test unless otherwise specified. Minimum/maximum limits at TA = -25°C and +85°C are guaranteed by design and characterization. There is no power-on register settings self-reset; recommended register settings must be loaded after V<sub>CC</sub> is applied.
- Note 2: Minimum/maximum limit is guaranteed by design and characterization.
- Note 3: It is currently not recommended and not tested. For test coverage support, contact manufacturer.
- **Note 4:** For optimal Rx and Tx quadrature accuracy over temperature, the user can utilize the Rx calibration and Tx calibration circuit to assist quadrature calibration.

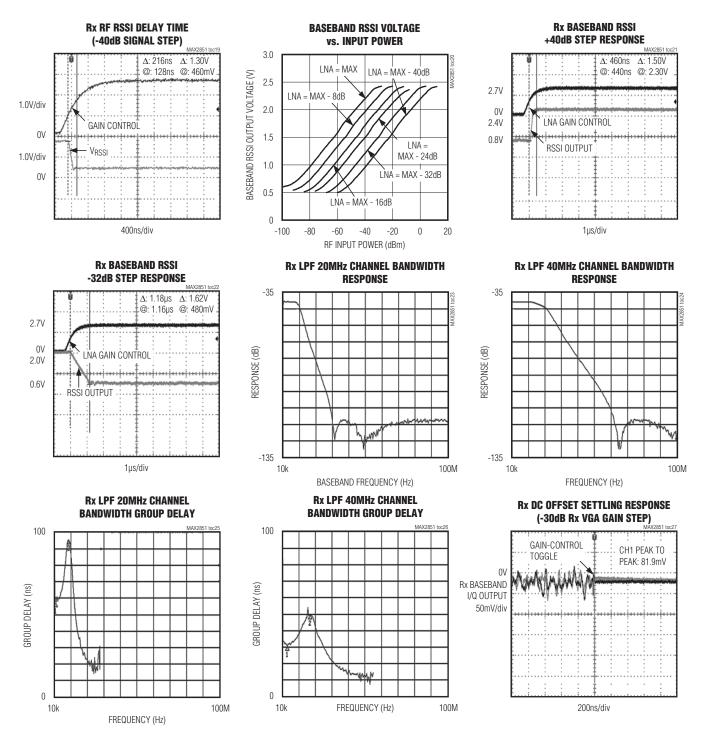
### **Typical Operating Characteristics**



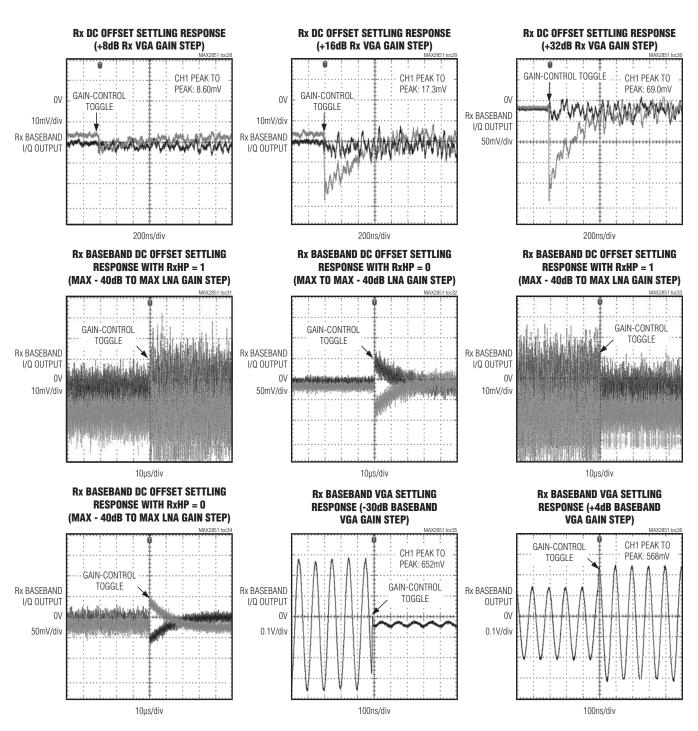
## Typical Operating Characteristics (continued)



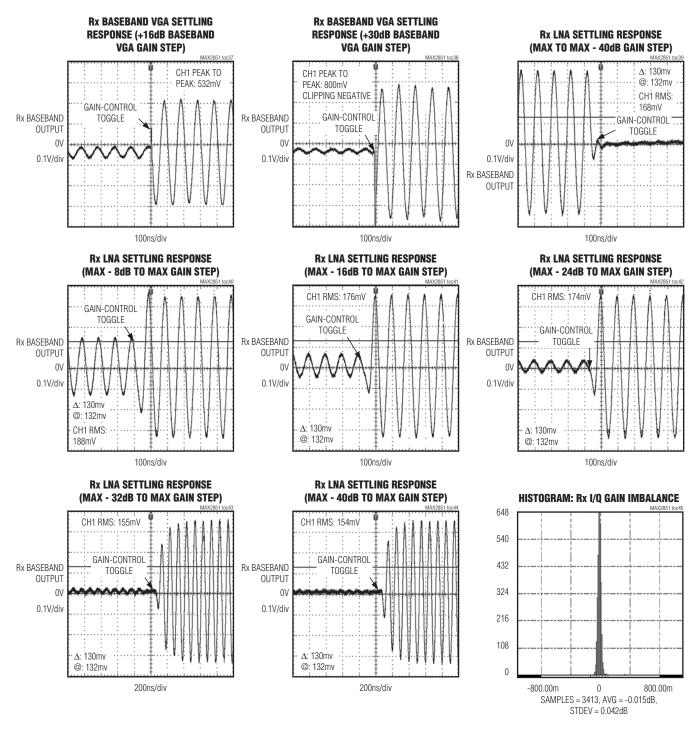
### Typical Operating Characteristics (continued)



### **Typical Operating Characteristics (continued)**

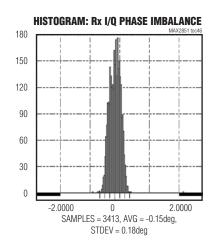


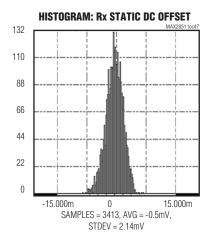
#### Typical Operating Characteristics (continued)

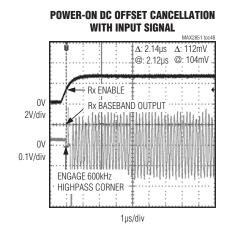


#### **Typical Operating Characteristics (continued)**

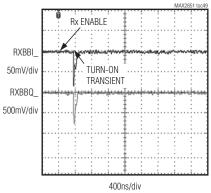
 $(V_{CC} = 2.8V, T_A = +25^{\circ}C, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at <math>50\Omega$  unbalanced output of balun, using the MAX2851 Evaluation Kit, unless otherwise noted.)

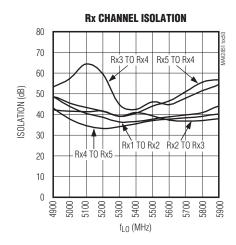




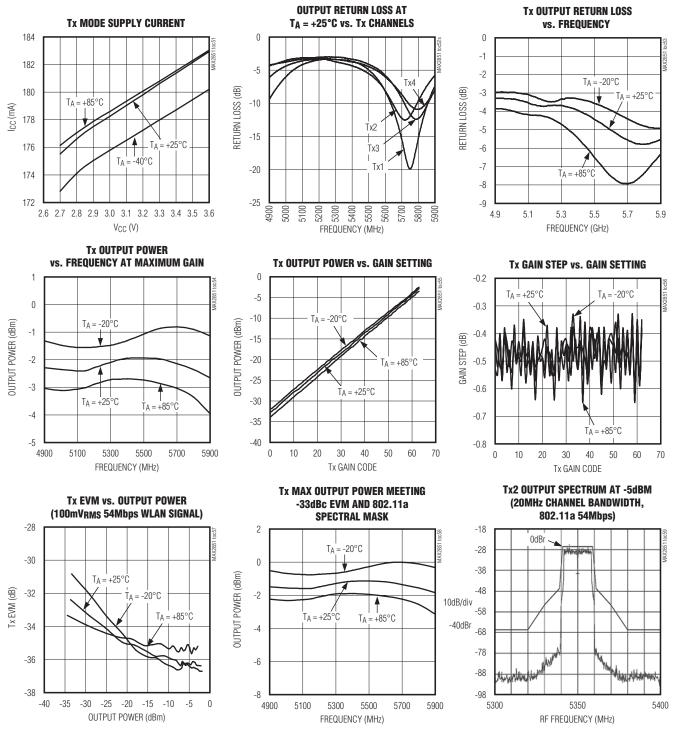


# POWER-ON DC OFFSET CANCELLATION WITHOUT INPUT SIGNAL

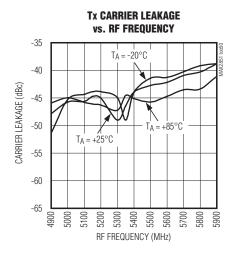


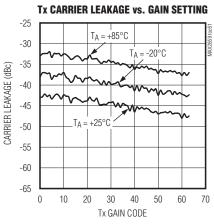


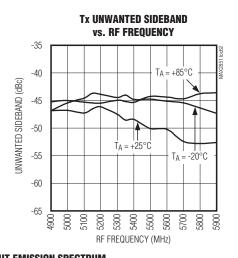
### **Typical Operating Characteristics (continued)**

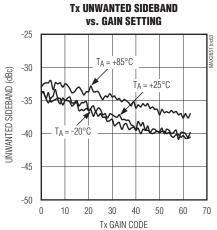


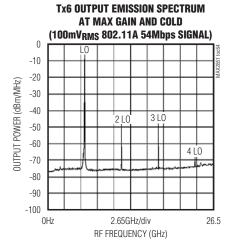
### Typical Operating Characteristics (continued)

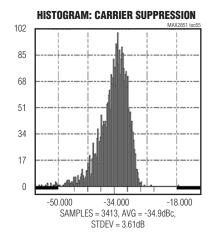


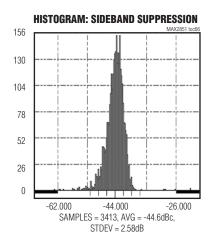




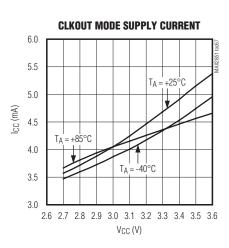


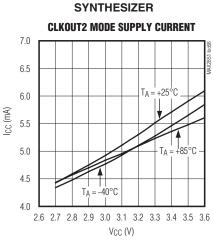


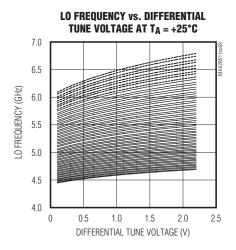


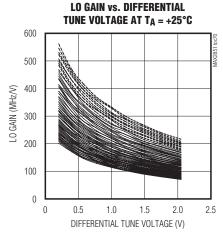


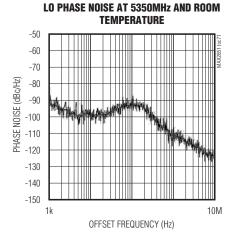
### Typical Operating Characteristics (continued)

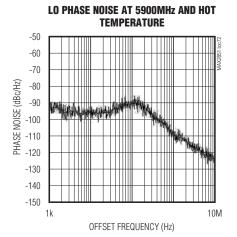


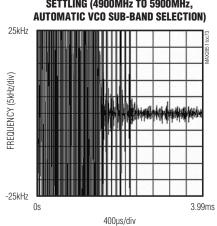










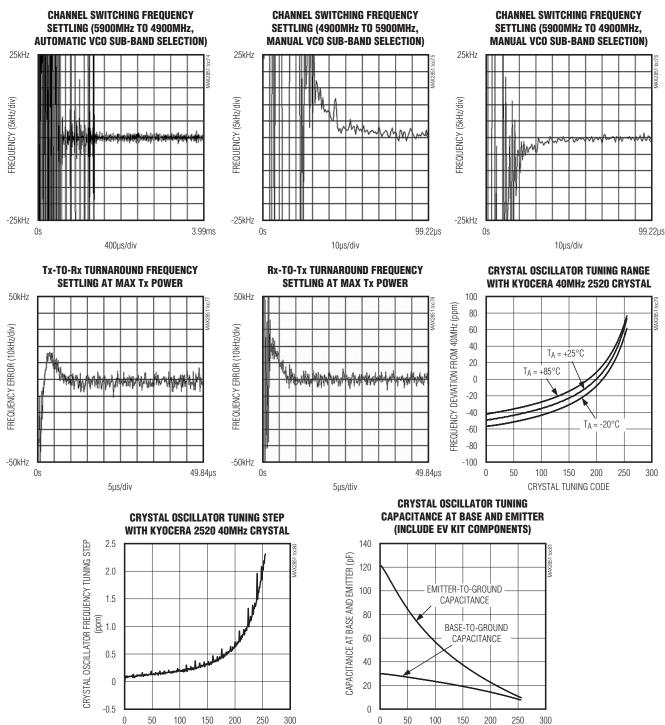


**CHANNEL SWITCHING FREQUENCY** SETTLING (4900MHz TO 5900MHz,

### Typical Operating Characteristics (continued)

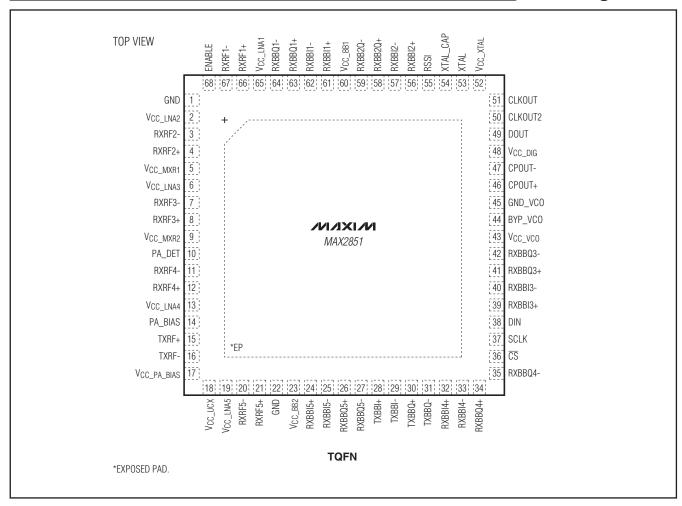
CRYSTAL TUNING CODE

 $(V_{CC} = 2.8V, T_A = +25^{\circ}C, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50<math>\Omega$  unbalanced output of balun, using the MAX2851 Evaluation Kit, unless otherwise noted.)



CRYSTAL TUNING CODE

## **Pin Configuration**



## Pin Description

PIN	NAME	FUNCTION				
1, 22	GND	Ground				
2	VCC_LNA2	Receiver 2 LNA Supply Voltage. Bypass with a capacitor as close as possible to the pin.				
3	RXRF2-					
4	RXRF2+	Receiver 2 LNA Differential Input. Input is DC-coupled and biased internally at 1.2V.				
5	VCC_MXR1	Receiver Downconverter Supply Voltage 1. Bypass with a capacitor as close as possible to the pin.				
6	VCC_LNA3	Receiver 3 LNA Supply Voltage. Bypass with a capacitor as close as possible to the pin.				
7	RXRF3-	Receiver 3 LNA Differential Input. Input is DC-coupled and biased internally at 1.2V.				
8	RXRF3+	neceiver 3 LINA differential imput. Imput is DC-coupled and biased internally at 1.24.				
9	VCC_MXR2	Receiver Downconverter Supply Voltage 2. Bypass with a capacitor as close as possible to the pin.				
10	PA_DET	External Power-Amplifier Detector Mux Input				
11	RXRF4-	Receiver 4 LNA Differential Input. Input is DC-coupled and biased internally at 1.2V.				
12	RXRF4+	Receiver 4 LINA Differential imput. Input is DC-coupled and biased internally at 1.2v.				
13	VCC_LNA4	Receiver 4 LNA Supply Voltage. Bypass with a capacitor as close as possible to the pin.				
14	PA_BIAS	External Power-Amplifier Voltage Bias Output				
15	TXRF+	Transmitter Differential Output. These pins are in open-collector configuration. These pins should				
16	TXRF-	be biased at the supply voltage with differential impedance terminated at $300\Omega$ .				
17	VCC_PA_	External Power-Amplifier Voltage Bias and Detector Mux Supply Voltage. Bypass with a capacitor				
17	BIAS	as close as possible to the pin.				
18	Vcc_ucx	ransmitter Upconverter Supply Voltage. Bypass with a capacitor as close as possible to the pi				
19	VCC_LNA5	Receiver 5 LNA Supply Voltage. Bypass with a capacitor as close as possible to the pin.				
20	RXRF5-	Descriver F. L.N.A. Differential Input. Input is DC coupled and bigged internally at 1.2V				
21	RXRF5+	Receiver 5 LNA Differential Input. Input is DC-coupled and biased internally at 1.2V.				
23	VCC_BB2	Receiver Baseband Supply Voltage 2. Bypass with a capacitor as close as possible to the pin.				
24	RXBBI5+	Receiver 5 Baseband I-Channel Differential Output				
25	RXBBI5-	neceivel 3 baseband i-Channel Dinerential Output				
26	RXBBQ5+	Receiver 5 Baseband Q-Channel Differential Output				
27	RXBBQ5-	neceivel 3 baseband Q-Channel Differential Output				
28	TXBBI+	Transmitter Baseband I-Channel Differential Input				
29	TXBBI-	Transmitter baseband r-Ghainner binierential imput				
30	TXBBQ+	Transmitter Baseband Q-Channel Differential Input				
31	TXBBQ-	Tanomittor basebana Q-onanner binerential input				
32	RXBBI4+	Receiver 4 Baseband I-Channel Differential Output				
33	RXBBI4-	Treceiver 4 Dasebanu r-Onanner Dinerential Output				
34	RXBBQ4+	Receiver 4 Baseband O-Channel Differential Output				
35	RXBBQ4-	Receiver 4 Baseband Q-Channel Differential Output				
36	CS	Active-Low Chip-Select Logic Input of 4-Wire Serial Interface				
37	SCLK	Serial-Clock Logic Input of 4-Wire Serial Interface				
38	DIN	Data Logic Input of 4-Wire Serial Interface				
39	RXBBI3+	Receiver 3 Baseband I-Channel Differential Output				
40	RXBBI3-	Necesses o baseband r-onamies binesential output				
41	RXBBQ3+	Receiver 3 Baseband Q-Channel Differential Output				
42	RXBBQ3-	neceivei o basebanu G-onannei binerentiai output				

## \_\_\_\_Pin Description (continued)

	T	
PIN	NAME	FUNCTION
43	Vcc_vco	VCO Supply Voltage. Bypass with a capacitor as close as possible to the pin.
44	BYP_VCO	On-Chip VCO Regulator Output Bypass. Bypass with an external 1µF capacitor to GND_VCO with minimum PCB trace. Do <b>not</b> connect other circuitry to this pin.
45	GND_VCO	VCO Ground
46	CPOUT+	Differential Charge-Pump Output. Connect the frequency synthesizer's loop filter between
47	CPOUT-	CPOUT+ and CPOUT- (see the Typical Operating Circuit).
48	Vcc_dig	Digital Block Supply Voltage. Bypass with a capacitor as close as possible to the pin.
49	DOUT	Data Logic Output of 4-Wire Serial Interface
50	CLKOUT2	Reference Clock Buffer Output 2
51	CLKOUT	Reference Clock Buffer Output
52	VCC_XTAL	Crystal Oscillator Supply Voltage. Bypass with a capacitor as close as possible to the pin.
53	XTAL	Crystal Oscillator Base Input. AC-couple crystal unit to this pin.
54	XTAL_CAP	Crystal Oscillator Emitter Node
55	RSSI	Receiver Signal Strength Indicator Output
56	RXBBI2+	Descriver a Reschand I Channel Differential Output
57	RXBBI2-	Receiver 2 Baseband I-Channel Differential Output
58	RXBBQ2+	Pagaivar 2 Pagaband O Channal Differential Output
59	RXBBQ2-	Receiver 2 Baseband Q-Channel Differential Output
60	VCC_BB1	Receiver Baseband Supply Voltage 1. Bypass with a capacitor as close as possible to the pin.
61	RXBBI1+	Receiver 1 Received I Channel Differential Output
62	RXBBI1-	Receiver 1 Baseband I-Channel Differential Output
63	RXBBQ1+	Receiver 1 Baseband Q-Channel Differential Output
64	RXBBQ1-	neceiver i basebanu Q-Channel billerentiai Output
65	VCC_LNA1	Receiver 1 LNA Supply Voltage. Bypass with a capacitor as close as possible to the pin.
66	RXRF1+	Pagaivar 1 LNA Differential limit Input in DC coupled and bissed internally at 1.0V
67	RXRF1-	Receiver 1 LNA Differential Input. Input is DC-coupled and biased internally at 1.2V.
68	ENABLE	Enable Logic Input
_	EP	Exposed Paddle. Connect to the ground plane with multiple vias for proper operation and heat dissipation. Do not share with any other pin grounds and bypass capacitors' ground.

**Table 1. Operating Modes** 

	MODE CONTI LOGIC INPU			CIRCUIT BLOCK STATES					
MODE	ENABLE PIN	SPI MAIN ADDRESS 0, D[4:2]	Rx PATH	Tx PATH (NOTE 1)	LO PATH	CLKOUT (NOTES 2, 3)	CALIBRATION SECTIONS ON		
SHUTDOWN	0	XXX	Off	Off	Off	Off	None		
CLOCKOUT	1	000	Off	Off	Off	On	None		
STANDBY	1	001	Off	Off	On	On	None		
Rx	1	010	On	Off	On	On	None		
Tx	1	011	Off	On	On	On	None		
Tx CALIBRATION	1	100	Off	On	On	On	AM detector + Rx5 I/Q buffers		
RF LOOPBACK	1	101	On (except LNA)	On	On	On	RF loopback		
BASEBAND LOOPBACK	1	11X	On (except RXRF)	Off	On	On	Tx baseband buffer		

Note 1: PA\_BIAS pin can be kept active in nontransmit mode(s) by SPI programming.

Note 2: CLKOUT signal is active independent of SPI, and is only dependent on the ENABLE pin.

Note 3: CLKOUT2 signal can be enabled/disabled through SPI in all operating modes except shutdown mode.

## **Detailed Description**

#### **Modes of Operation**

The MAX2851 modes of operation are shutdown, clockout, standby, receive, transmit, transmitter calibration, RF loopback, and baseband loopback. See Table 1 for a summary of the modes of operation. The logic input pin ENABLE (pin 68) and SPI Main address 0 D[4:2] control the various modes.

#### Shutdown Mode

The MAX2851 features a low-power shutdown mode. All circuit blocks are powered down, except the 4-wire serial bus and its internal programmable registers.

#### **Clockout Mode**

In clockout mode, only the crystal oscillator signal is active at the CLKOUT pin. The rest of the transceiver is powered down.

#### Standby Mode

In standby mode, PLL, VCO, and LO generation are on. Tx or Rx modes can be quickly enabled from this mode. Other blocks can be selectively enabled in this mode

#### Receive (Rx) Mode

In receive mode, all Rx circuit blocks are powered on and active. The antenna signal is applied; RF is down-converted, filtered, and buffered at the RXBB I and Q outputs.

#### Transmit (Tx) Mode

In transmit mode, all Tx circuit blocks are powered on and active. The external PA can be powered on through the PA\_BIAS pin after a programmable delay.

#### Transmit Calibration Mode

In transmit calibration mode, all Tx circuit blocks are powered on and active. The AM detector and receiver I/Q channel buffers are also on. Output signals are routed to RXBB I and Q outputs.

The AM detector multiplies the Tx RF output signal with itself. The self-mixing product of the wanted sideband becomes DC voltage and is filtered on-chip. The mixing product between wanted sideband and the carrier leakage forms Ftone at the Rx baseband output. The mixing product between the wanted sideband and the unwanted sideband forms 2Ftone at the Rx baseband output.

As the Tx RF output is self-mixed at the AM detector, the AM detector output responds differently to different gain settings and power levels. When the Tx RF output power changes by 1dB through Tx gain control, the AM detector output changes by 2dB as both the wanted sideband and carrier leakage (or unwanted sideband) change by 1dB. When Tx RF output carrier leakage (or unwanted sideband) changes by 1dB while the wanted sideband output power is constant, the AM detector output changes by 1dB only.

#### RF Loopback Mode

In RF loopback mode, part of the Rx and Tx circuit blocks except the LNA are powered on and active. The transmitter I/Q input signal is upconverted to RF, and the output of the transmitter is fed to the receiver downconverter input. Output signals are delivered to all receiver baseband I/Q outputs. The I/Q lowpass filters in the transmitter signal path are bypassed.

#### Baseband Loopback Mode

In baseband loopback mode, part of the Rx and Tx baseband circuit blocks are powered and active. The transmitter I/Q input signal is routed to the receiver low-pass filter input. Output signals are delivered to receiver 5 baseband I/Q outputs.

#### Power-On Sequence

Set the ENABLE pin to VCC for 2ms to start the crystal oscillator. Program all SPI addresses according to recommended values. Set SPI Main address 0 D[4:2] from 000 to 001 to engage standby mode. To lock the LO frequency, the user can set SPI in order of Main address 15, Main address 16, and then Main address 17 to trigger VCO sub-band autoacquisition; the acquisition takes 2ms. After the LO frequency is locked, set SPI Main address 0 D[4:2] = 010 and 011 for Rx and Tx operating modes, respectively. Before engaging to Rx mode, set Main address 5 D1 = 1 to allow fast DC-offset settling. After engaging to Rx mode and the Rx baseband DC

offset settles, the user can set Main address 5 D1 = 0 to complete Rx DC-offset cancellation.

#### Programmable Registers and 4-Wire SPI Interface

The MAX2851 includes 60 programmable 16-bit registers. The most significant bit (MSB) is the read/write selection bit (R/W in Figure 1). The next 5 bits are register address (A[4:0] in Figure 1). The 10 least significant bits (LSBs) are register data (D[9:0] in Figure 1). Register data is loaded through the 4-wire SPI/MICROWIRETMcompatible serial interface. MSB of data at the DIN pin is shifted in first and is framed by  $\overline{CS}$ . When  $\overline{CS}$  is low, the clock is active and input data is shifted at the rising edge of the clock at the SCLK pin. At  $\overline{\text{CS}}$  rising edge. the 10-bit data bits are latched into the register selected by the address bits. See Figure 1. To support more than a 32-register address using a 5-bit-wide address word. the bit 0 of address 0 is used to select whether the 5-bit address word is applied to the main address or local address. There is **no** power-on SPI register self-reset functionality in the MAX2851; the user must program all register values after power-up. During the read mode, register data selected by address bits is shifted out to the DOUT pin at the falling edges of the clock.

MICROWIRE is a trademark of National Semiconductor Corp.

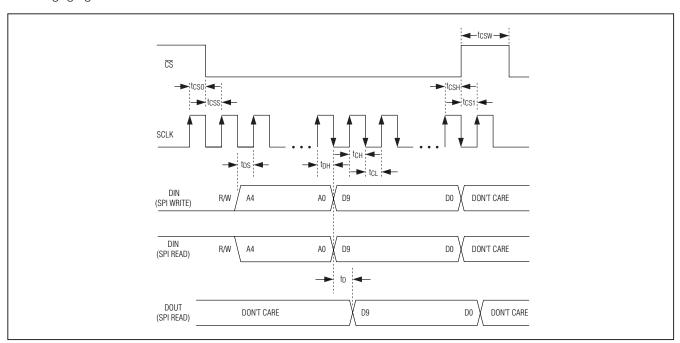


Figure 1. 4-Wire SPI Serial-Interface Timing Diagram

## **SPI Register Definition**

All values in the register definition table are typical numbers. The MAX2851 SPI does not have a power-

on-default self-reset feature; the user must program all SPI addresses for normal operation. Prior to use of any untested settings, contact the factory.

### **Table 2. Register Summary**

REGISTER	READ/WRITE AND ADDRESS							DATA						
REGISTER	MAINO_ D0	A[4:0]	WRITE (W)/ READ (R)	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
M : 0		00000	W/R			RESERVE	D	•		MODE[2:0]		RFBW	M/L_SEL	
Main 0	0	00000	Default	0	0	0	0	1	0	0	0	1	0	
NA 1 4	_	00004	W/R	RESERV	ED	LI	VA_GAIN	[2:0]		V	GA_GAIN[4:	:0]		
Main 1	0	00001	Default	0	0	1	1	1	1	1	1	1	1	
		00040	W/R	RES	SERVE	)	LNA_B	AND[1:0]			RESERVED			
Main 2	0	00010	Default	0	1	1	0	1	0	0	0	0	0	
			W	DEOEDU		TO 511	TS_	DE0ED / ED			RESERVED			
Main 3	0	00011	R	RESERV	ED	TS_EN	TRIG	RESERVED		-	TS_READ[4:0	 D]		
			Default	0	0	0	0	0	0	0	0	0	0	
Main 4	0	00100	Reserved	1	1	0	0	0	1	1	1	0	0	
		00101	W/R	RESERVED	RSS	SI_MUX_S	EL[2:0]	RS	SI_RX_SEL[	2:0]	RESERVED	RXHP	RESERVED	
Main 5	0	00101	Default	0	0	0	0	0	0	0	0	0	0	
		00110	W/R		RX_GA	IN_PROG	_SEL[5:1]		E_RX					
Main 6	0	00110	Reserved	1	1	1	1	1	1	1	1	1	1	
Main 7	0	00111	Reserved	0	0	0	0	1	0	0	1	0	0	
Main 8	0	01000	W/R	0	0	0	0	0	0	0	0	0	0	
M : 0		04004	W/R			TX_GAIN[5:0]			RESI			ERVED		
Main 9	0	01001	Default	0	0	0	0	0	0	1	1	1	1	
Main 10	0	01010	Reserved	0	0	0	0	0	0	0	0	0	0	
		0.404.4	W/R					R	ESERVED					
Main 11	0	01011	Default	0	0	0	1	1	0	0	0	0	0	
Main 13	0	01101	Reserved	0	0	0	0	0	0	0	0	0	0	
M : 44	_	01110	W/R	E_CLKOUT2				RESER	VED			DOUT_SEL	RESERVED	
Main 14	0	01110	Default	1	1	0	1	1	0	0	0	0	0	
Main 15	0	01111	W/R	VAS_ TRIG_EN	RES	SERVED			SYI	SYN_CONFIG_N[6:0]			•	
			Default	1	0	0	1	0	0	0	0	1	0	
	_		W/R					SYN_C	DNFIG_F[19	IG_F[19:10]				
Main 16	0	10000	Default	1	1	1	0	0	0	0	0	0	0	
	_		W/R					SYN_C	CONFIG_F[9	9:0]				
Main 17	0	10001	Default	0	0	0	0	0	0	0	0	0	0	
M : 12	_	10015	W/R	RESERV	ED.				XTAL_	_TUNE[7:0]				
Main 18	0	10010	Default	0	0	1	0	0	0	0	0	0	0	

**Table 2. Register Summary (continued)** 

	READ/WRITE AND ADDRESS				DATA								
REGISTER	MAINO_ D0	A[4:0]	WRITE (W)/ READ (R)	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Main 19	0	10011	W/R	RESERV	ED	VAS_ RELOCK_ SEL	VAS_ MODE			VAS_S	SPI[5:0]		
			Read	RESERVED	١ ١	VAS_ADC[	2:0]			VCO_B	AND[5:0]		
			Default	0	0	0	1	0	1	1	1	1	1
Main 20	0	10100	Reserved	0	1	1	1	1	0	1	0	1	0
Main Od	_	10101	Read	RESERV	ED		DIE_ID[2:	0]			RESERVED		
Main 21	0	10101	Default	0	0	1	0	1	1	1	1	1	1
Main 22	0	10110	Reserved	0	1	1	0	1	1	1	0	0	0
Main 23	0	10111	Reserved	0	0	0	1	1	0	0	1	0	1
Main 24	0	11000	Reserved	1	0	0	1	0	0	1	1	1	1
Main 25	0	11001	Reserved	1	1	1	0	1	0	1	0	0	0
Main 26	0	11010	Reserved	0	0	0	0	0	1	0	1	0	1
Main 27	0	11011	W/R	DIE_ID_ READ		RESERVE	ĒD	VAS_VCO_ READ			RESERVED		
			Default	0	1	1	0	0	0	0	0	0	0
Maia 00	_	11100	W/R			RES	SERVED	VED PA_BIAS					
Main 28	0	11100	Default	0	0	0	1	1	0	0	0	1	1
Main 29	0	11101	Reserved	0	0	0	0	0	0	0	0	0	0
Main 30	0	11110	Reserved	0	0	0	0	0	0	0	0	0	0
Main 31	0	11111	Reserved	0	0	0	0	0	0	0	0	0	0
Local 1	1	00001	Reserved	0	0	0	0	0	0	0	0	0	0
Local 2	1	00010	Reserved	0	0	0	0	0	0	0	0	0	0
Local 3	1	00011	Reserved	0	0	0	0	0	0	0	0	0	0
1 1 4	_	00100	W/R	RFDET_N	MUX_SE	EL[2:0]				RESERVE	D		
Local 4	1	00100	Reserved	1	1	1	0	0	0	0	0	0	0
Local 5	1	00101	Reserved	0	0	0	0	0	0	0	0	0	0
Local 6	1	00110	Reserved	0	0	0	0	0	0	0	0	0	0
Local 7	1	00111	Reserved	0	0	0	0	0	0	0	0	0	0
Local 8	1	01000	Reserved	0	1	1	0	1	0	1	0	1	0
Local 9	1	01001	Reserved	0	1	0	0	0	1	0	1	0	0
Local 10	1	01010	Reserved	1	1	0	1	0	1	0	1	0	0
Local 11	1	01011	Reserved	0	0	0	1	1	1	0	0	1	1
Local 12	1	01100	Reserved	0	0	0	0	0	0	0	0	0	0
Local 13	1	01101	Reserved	0	0	0	0	0	0	0	0	0	0
Local 14	1	01110	Reserved	0	0	0	0	0	0	0	0	0	0
Local 15	1	01111	Reserved	0	0	0	0	0	0	0	0	0	0
Local 16	1	10000	Reserved	0	0	0	0	0	0	0	0	0	0
Local 17	1	10001	Reserved	0	0	0	0	0	0	0	0	0	0

**Table 2. Register Summary (continued)** 

REGISTER	READ/WRITE AND ADDRESS		DATA										
REGISTER	MAINO_ D0	A[4:0]	WRITE (W)/ READ (R)	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Local 18	1	10010	Reserved	0	0	0	0	0	0	0	0	0	0
Local 19	1	10011	Reserved	0	0	0	0	0	0	0	0	0	0
Local 20	1	10100	Reserved	0	0	0	0	0	0	0	0	0	0
Local 21	1	10101	Reserved	0	0	0	0	0	0	0	0	0	0
Local 22	1	10110	Reserved	0	0	0	0	0	0	0	0	0	0
Local 23	1	10111	Reserved	0	0	0	0	0	0	0	0	0	0
Local 24	1	11000	Reserved	0	0	1	1	0	0	0	1	0	0
Local 25	1	11001	Reserved	0	1	0	0	1	0	1	0	1	1
Local 26	1	11010	Reserved	0	1	0	1	1	0	0	1	0	1
Local 27	1	11011	W/R	RESERVED TX_AMD_ TX_A BB_GAIN RF_G					AMD_ GAIN				
			Default	0	0	0	0	0	0	0	0	0	0
Local 28	1	11100	Reserved	0	0	0	0	0	0	0	1	0	0
Local 31	1	11111	Reserved	0	0	0	0	0	0	0	0	0	0

Table 3. Main Address 0 (A[4:0] = 00000)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:5]	Reserved bits—set to default.
MODE[2:0]	D[4:2]	IC operating mode select.  000 = Clockout (default)  001 = Standby  010 = Rx  011 = Tx  100 = Tx calibration  101 = RF loopback  11x = Baseband loopback
RFBW	D1	RF bandwidth. 0 = 20MHz 1 = 40MHz (default)
M/L_SEL	D0	Main or local address select.  0 = Main registers (default)  1 = Local registers

Table 4. Main Address 1 (A[4:0] = 00001, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:8]	Reserved bits—set to default.
LNA_GAIN[2:0]	D[7:5]	LNA gain control. Active when Rx channel is selected by corresponding RX_GAIN_PROG_SEL[5:1] bits in Main address 6 D[9:5].  000 = Max - 40dB  001 = Max - 32dB  100 = Max - 24dB (not tested, contact factory for coverage)  101 = Max - 16dB  110 = Max - 8dB  111 = Max gain (default)
VGA_GAIN[4:0]	D[4:0]	Rx VGA gain control. Active when Rx channel is selected by corresponding RX_GAIN_PROG_SEL[5:1] bits in Main address 6 D[9:5].  00000 = Min gain  00001 = Min + 2dB  01110 = Min + 28dB  01111 = Min + 30dB  1xxxx = Min + 30dB (default)

Table 5. Main Address 2 (A[4:0] = 00010, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:7], D[4:0]	Reserved bits—set to default.
LNA_BAND[1:0]	D[6:5]	LNA frequency band switch.  00 = 4.9GHz~5.2GHz  01 = 5.2GHz~5.5GHz (default)  10 = 5.5GHz~5.8GHz  11 = 5.8GHz~5.9GHz

### Table 6. Main Address 3 (A[4:0] = 00011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:8], D5	Reserved bits—set to default.
TS_EN	D7	Temperature sensor enable.  0 = Disable (default)  1 = Enable except shutdown or clockout mode
TS_TRIG	D6	Temperature sensor reading trigger.  0 = Not trigger (default)  1 = Trigger temperature reading
TS_READ[4:0] (Readback Only)	D[4:0]	SPI readback only. Temperature sensor reading.

## Table 7. Main Address 5 (A[4:0] = 00101, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9, D2, D0	Reserved bits—set to default.
RSSI_MUX_SEL[2:0]	D[8:6]	RSSI output select.  000 = Baseband RSSI (default)  001 = Do not use  010 = Do not use  011 = Do not use  100 = Rx RF detector  101 = Do not use  110 = PA power-detector mux output  111 = Do not use

Table 7. Main Address 5 (A[4:0] = 00101, Main Address 0 D0 = 0) (continued)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RSSI_RX_SEL[2:0]	D[5:3]	Baseband RSSI Rx channel select.  000 = Not select (default)  001 = Rx1  010 = Rx2  011 = Rx3  100 = Rx4  101 = Rx5  110 = Do not use  111 = Do not use
RXHP	D1	Rx VGA highpass corner select after Rx turn-on. RXHP starts at 1 during Rx gain adjustment and set 0 after gain is adjusted.  0 = 10kHz highpass corner after Rx gain is adjusted (default)  1 = 600kHz highpass corner during Rx gain adjustment

## Table 8. Main Address 6 (A[4:0] = 00110, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RX_GAIN_PROG_SEL [5:1]	D[9:5]	Rx channel gain programming select. Select which Rx channels are to be changed; gain is then determined by programming Main address 1 D[7:0]. D9 selects Rx5, D8 selects Rx4, etc. 0 = Not selected 1 = Selected 11111 = Default
E_RX[5:1]	D[4:0]	Rx MIMO channel select. Enable Rx channels independently. D4 selects Rx5, D3 selects Rx4, etc. 0 = Not selected 1 = Select in Rx, RF loopback, or Tx calibration mode 11111 = Default

## Table 9. Main Address 9 (A[4:0] = 01001, Main Address 0 D0 = 0)

	`	
BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
TX_GAIN[5:0]	D[9:4]	Tx VGA gain control. Tx channel is selected by Main address 9 D[3:0].  000000 = Min gain (default)  111111 = Min gain + 31.5dB
RESERVED	D[3:0]	Reserved bits—set to default.

Table 10. Main Address 14 (A[4:0] = 01110, Main Address 0 D0 = 0

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
E_CLKOUT2	D9	CLKOUT2 enable. 0 = Disable 1 = Enable except during shutdown mode (default)
RESERVED	D[8:2], D1	Reserved bits—set to default.
DOUT_SEL	D1	DOUT pin output select. 0 = PLL lock detect (default) 1 = SPI readback

## Table 11. Main Address 15 (A[4:0] = 01111, Main Address 0 D0 = 0)

		-
BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
VAS_TRIG_EN	D9	Enable VCO sub-band acquisition triggerred by SYN_CONFIG_F[9:0] (Main address 17) programming.  0 = Disable for small frequency adjustment (i.e., ~100kHz).  1 = Enable for channel switching (default)
RESERVED	D[8:7]	Reserved bits—set to default.
SYN_CONFIG_N[6:0]	D[6:0]	Integer divide ratio. 1000010 = Default

### Table 12. Main Address 16 (A[4:0] = 10000, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
SYN_CONFIG_F[19:10]	D[9:0]	Fractional divide ratio MSBs. 1110000000 = Default

### Table 13. Main Address 17 (A[4:0] = 10001, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
SYN_CONFIG_F[9:0]	D[9:0]	Fractional divide ratio LSBs. 0000000000 = Default

### Table 14. Main Address 18 (A[4:0] = 10010, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:8]	Reserved bits—set to default.
XTAL_TUNE[7:0]	D[7:0]	Crystal oscillator frequency tuning.  00000000 = Min frequency  10000000 = Default  11111111 = Max frequency

## Table 15. Main Address 19 (A[4:0] = 10011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:8]	Reserved bits—set to default.
VAS_RELOCK_SEL	D7	VAS relock select. 0 = Start at sub-band selected by VAS_SPI[5:0] (Main address 19 D5:D0) (default) 1 = Start at current sub-band
VAS_MODE	D6	VCO sub-band select. 0 = By VAS_SPI[5:0] (Main address 19 D[5:0]) 1 = By on-chip VCO autoselect (VAS) (default)
VAS_SPI[5:0]	D[5:0]	VCO autoselect sub-band input. Select VCO subband when VAS_MODE (Main address 19 D6) = 0. Select initial VCO sub-band for auto-acquisition when VAS_MODE = 1.  000000 = Min frequency sub-band  011111 = Default  111111 = Max frequency sub-band
VAS_ADC[2:0] (Readback Only)	D[8:6]	Read VCO autoselect tune voltage ADC output. Active when VAS_VCO_READ (Main address 27 D5) = 1.  000 = Lower than lock range and at risk of unlock 001 = Lower than acquisition range and maintain lock 010 or 101 = Within acquisition range and maintain lock 110 = Higher than acquisition range and maintain lock 111 = Higher than lock range and at risk of unlock
VCO_BAND[5:0] (Readback Only)	D[5:0]	Read the current acquired VCO sub-band by VCO autoselect. Active when VAS_VCO_READ (Main address 27 D5) = 1.

### Table 16. Main Address 21 (A[4:0] = 10101, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:8], D[4:0]	Reserved bits—set to default.
DIE_ID[2:0] (Readback Only)	D[7:5]	Read revision ID at Main address 21 D[7:5]. Active when DIE_ID_READ (Main address 27 D9) = 1. 000 = Pass1 001 = Pass2

Table 17. Main Address 27 (A[4:0] = 11011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
DIE_ID_READ	D9	Die ID readback select.  0 = Main address 21 D[9:0] reads its own values (default)  1 = Main address 21 D[7:5] reads revision ID
RESERVED	D[8:6], D[4:0]	Reserved bits—set to default.
VAS_VCO_READ	D5	VAS ADC and VCO sub-band readback select.  0 = Main address 19 D[9:0] reads its own values (default)  1 = Main address 19 D[8:6] reads VAS_ADC[2:0]; Main address 19  D[5:0] reads VCO_BAND[5:0]

Table 18. Main Address 28 (A[4:0] = 11100, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:4]	Reserved bits—set to default.
PA_BIAS_DLY[3:0]	D[3:0]	PA_BIAS turn-on delay.  0000 = 0µs  0001 = 0µs  0010 = 0.5µs  0011 = 1.0µs (default)  1111 = 7.0µs  Only default is tested; contact factory for test coverage.

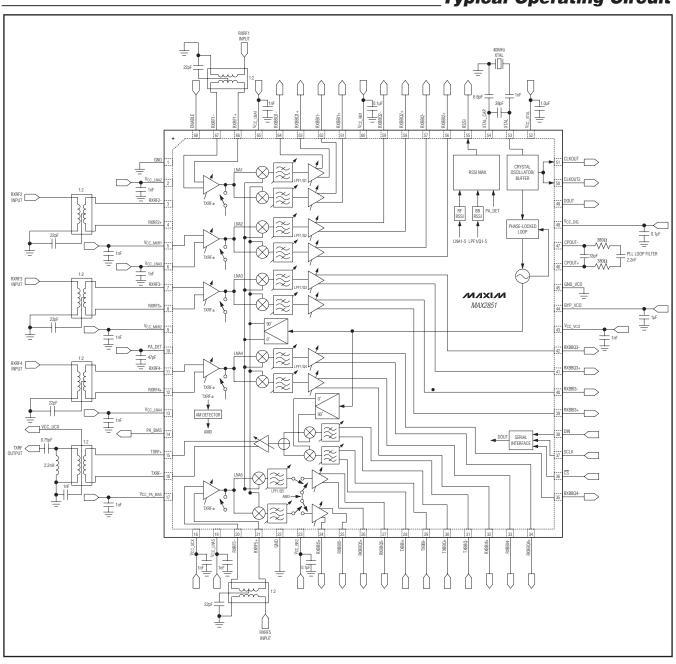
Table 19. Local Address 4 (A[4:0] = 00100, Main Address 0 D0 = 1)

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BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RFDET_MUX_SEL[2:0]	D[9:7]	RF RSSI channel selection.  000 = Rx1  001 = Rx2  010 = Rx3  011 = Rx4  100 = Rx5  101 = Do not use  110 = Do not use  111 = Not selected (default)
RESERVED	D[6:0]	Reserved bits—set to default.

## Table 20. Local Address 27 (A[4:0] = 11011, Main Address 0 D0 = 1)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D[9:3]	Reserved bits—set to default.
TX_AMD_BB_GAIN	D2	Tx calibration AM detector baseband gain.  0 = Minimum gain (default)  1 = Minimum gain + 5dB
TX_AMD_RF_GAIN	D[1:0]	Tx calibration AM detector RF gain.  00 = Minimum gain (default)  01 = Minimum gain + 14dB rise at output  1x = Minimum gain + 28dB rise at output

## **Typical Operating Circuit**



PROCESS: BICMOS

# 5GHz, 5-Channel MIMO Receiver

Chip Information

### Package Information

For the latest package outline information and land patterns, go to <a href="www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
68 TQFN-EP	T6800+2	21-0142

MIXIM

## **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	1/10	Initial release	_
1	3/10	Modified EC table to support single-pass room test flow	2, 3, 5, 6–9

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